

TLC59116-Q1 16-Channel FM+ I²C-Bus Constant-Current LED Sink Driver

1 Features

- 16 LED Drivers (Each Output Programmable at Off, On, Programmable LED Brightness, or Programmable Group Dimming and Blinking Mixed With Individual LED Brightness)
- 16 Constant-Current Output Channels
- 256-Step (8-Bit) Linear Programmable Brightness Per LED Output Varying From Fully Off (Default) to Maximum Brightness Using a 97-kHz PWM Signal
- 256-Step Group Brightness Control Allows General Dimming [Using a 190-Hz PWM Signal From Fully Off to Maximum Brightness (Default)]
- 256-Step Group Blinking With Frequency Programmable From 24-Hz to 10.73 s and Duty Cycle From 0% to 99.6%
- Four Hardware Address Pins Allow 14 TLC59116-Q1 Devices to Be Connected to Same I²C Bus
- Four Software-Programmable I²C Bus Addresses (One LED Group Call Address and Three LED Sub Call Addresses) Allow Groups of Devices to Be Addressed at Same Time in Any Combination
- Software Reset Feature (SWRST Call) Allows Device to Be Reset Through I²C Bus
- Up to 14 Possible Hardware-Adjustable Individual I²C Bus Addresses Per Device, So That Each Device Can Be Programmed
- Open-Load and Overtemperature Detection Mode to Detect Individual LED Errors
- Output State Change Programmable on Acknowledge or Stop Command to Update Outputs Byte-by-Byte or All at Same Time (Default to Change on Stop)
- Output Current Adjusted Through an External Resistor
- Constant Output Current Range: 5-mA to 120-mA
- Maximum Output Voltage: 17 V
- 25-MHz Internal Oscillator Requires No External Components
- 1-MHz Fast-mode Plus (FMT) Compatible I²C-Bus Interface With 30-mA High-Drive Capability on SDA Output for Driving High-Capacitive Buses
- Internal Power-On Reset
- Noise Filter on SCL and SDA Inputs
- No Glitch on Power-Up
- Active-Low Reset
- Supports Hot Insertion
- Low Standby Current

- 3.3 V or 5 V Supply Voltage
- 5.5 V Tolerant Inputs
- 28-Pin Thin Shrink Small-Outline Package (TSSOP) (PW-28)
- –40°C to +105°C Operation

2 Applications

- General LED Lighting Applications
- Backlight for center stack buttons
- Backlight for cluster indicators

3 Description

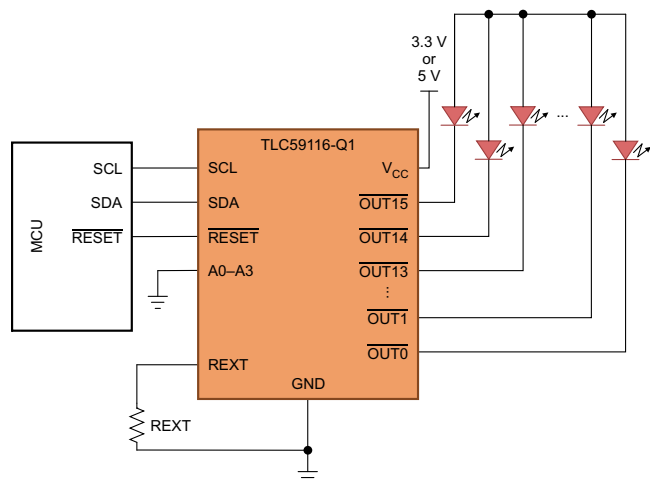
The TLC59116-Q1 is an I²C-Bus controlled 16-channel LED driver that is optimized for red/green/blue/amber (RGBA) color mixing and backlight application. Each LED output has its own 8-bit resolution (256 steps) fixed-frequency individual PWM controller that operates at 97 kHz, with a duty cycle that is adjustable from 0% to 99.6%.

Device Information (1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
TLC59116-Q1	TSSOP (28)	9.70 mm x 4.40 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

TLC59116-Q1 Typical Application



4 Description (continued)

The individual PWM controller allows each LED to be set to a specific brightness value. An additional 8-bit resolution (256 steps) group PWM controller has both a fixed frequency of 190-Hz and an adjustable frequency between 24-Hz to once every 10.73 seconds, with a duty cycle that is adjustable from 0% to 99.6%. The group PWM controller dims or blinks all LEDs with the same value.

Each LED output can be off, on (no PWM control), or set at its individual PWM controller value at both individual and group PWM controller values.

The TLC59116-Q1 operates with a supply voltage range of 3 V to 5.5 V and the outputs are 17 V tolerant. LEDs can be directly connected to the TLC59116-Q1 device outputs.

Software programmable LED Group and three Sub Call I²C-Bus addresses allow all or defined groups of TLC59116-Q1 devices to respond to a common I²C Bus address, allowing for example, all the same color LEDs to be turned on or off at the same time or marquee chasing effect, thus minimizing I²C Bus commands.

Four hardware address pins allow up to 14 devices on the same Bus.

The Software Reset (SWRST) Call allows the master to perform a reset of the TLC59116-Q1 through the I²C Bus, identical to the Power-On Reset (POR) that initializes the registers to their default state causing the outputs to be set high (LED off). This allows an easy and quick way to reconfigure all device registers to the same condition.

5 Device and Documentation Support

5.1 Documentation Support

5.1.1 Related Documentation

For related documentation see the following:

- TLC59116EVM-390 User's Guide, [SLVU296](#)
- TLC59116FEVM-571, [SLVU367](#)

5.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

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5.3 Trademarks

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5.4 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

5.5 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TLC59116ITPWRQ1	PREVIEW	TSSOP	PW	28	2000	TBD	Call TI	Call TI	-40 to 105		
TLC59116ITPWTQ1	PREVIEW	TSSOP	PW	28	2000	TBD	Call TI	Call TI	-40 to 105		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

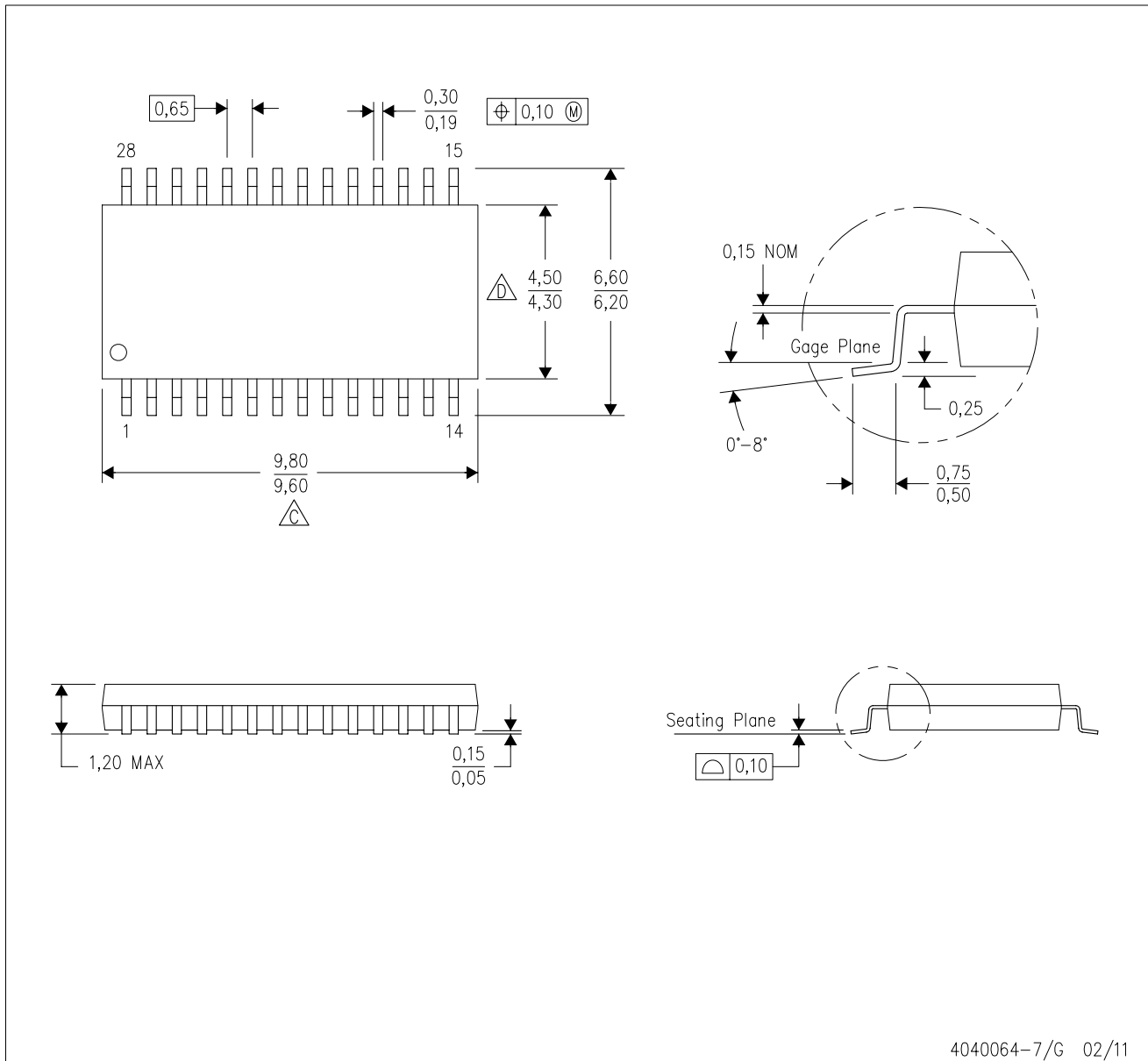
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MECHANICAL DATA

PW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



4040064-7/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

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